

A switchboard for valuable signals, the UQDS and PDSU patch panels ...

TE-MPE-EP

Vito Vizziello

21/01/2025

What is the UQDS and PDSU patch panel

For the upgrade of the LHC to HL-LHC, the **patch panel** represents an element of the **Quench Detection System** that accomplishes the complex aim of mapping multiple signal sources to multiple destinations.

Importance of Patch Panel during Hi-Lumi

ELQA measurements can be done, at any moment, directly from the Patch Panel if radiation level around IFS boxes placed on the magnet cold mass are high.

ELQA measurements can be provided without the need to disconnect the quench detection system.

Patch Panel

Conveying all the needed signals from several IFS boxes directly to each specific UQDS.

Possibility to use a standard hardware configuration for UQDS with fewer risks to make mistakes with the cabling.

Optimizing the time and make it easy during the local interventions.

General architecture of the Patch Panel

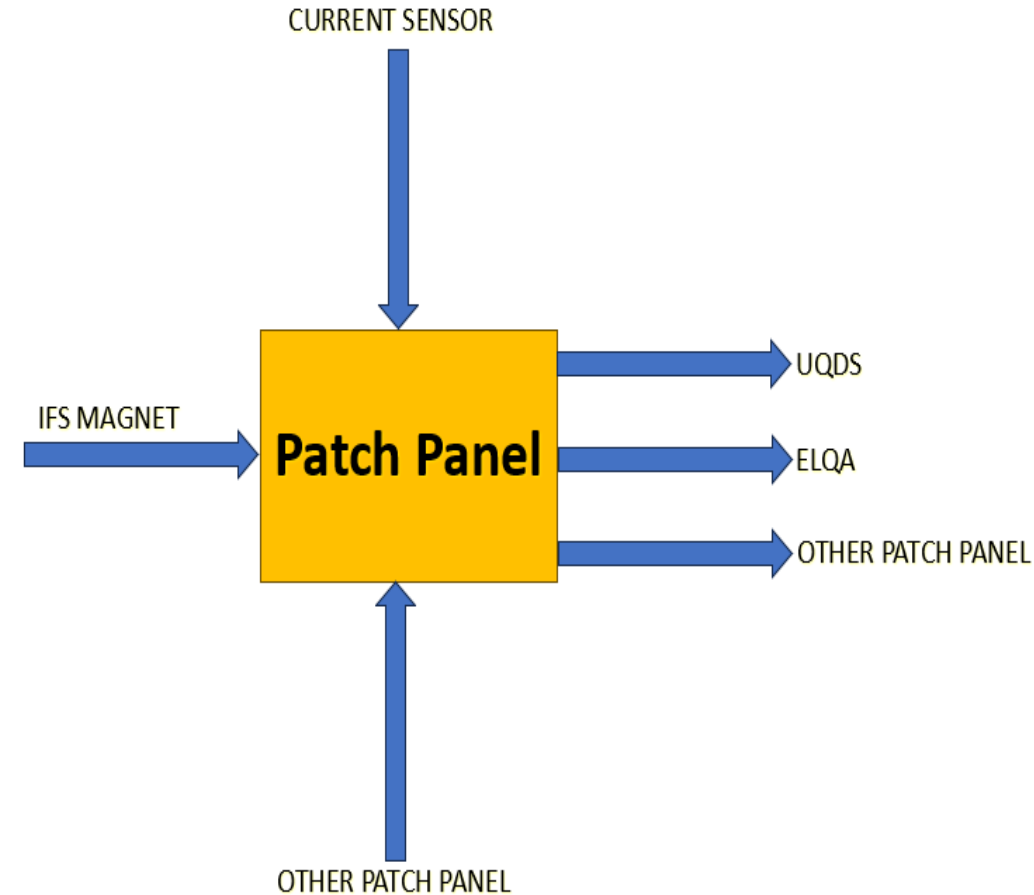
The Patch Panel collects INPUT signals from:

- IFS boxes of the magnets
- The current sensor boxes
- Another patch panel from a different rack.

Internally the patch panel is routed for driving each single INPUT signal to a specific OUTPUT.

The Patch Panel dispatches OUTPUT signals to:

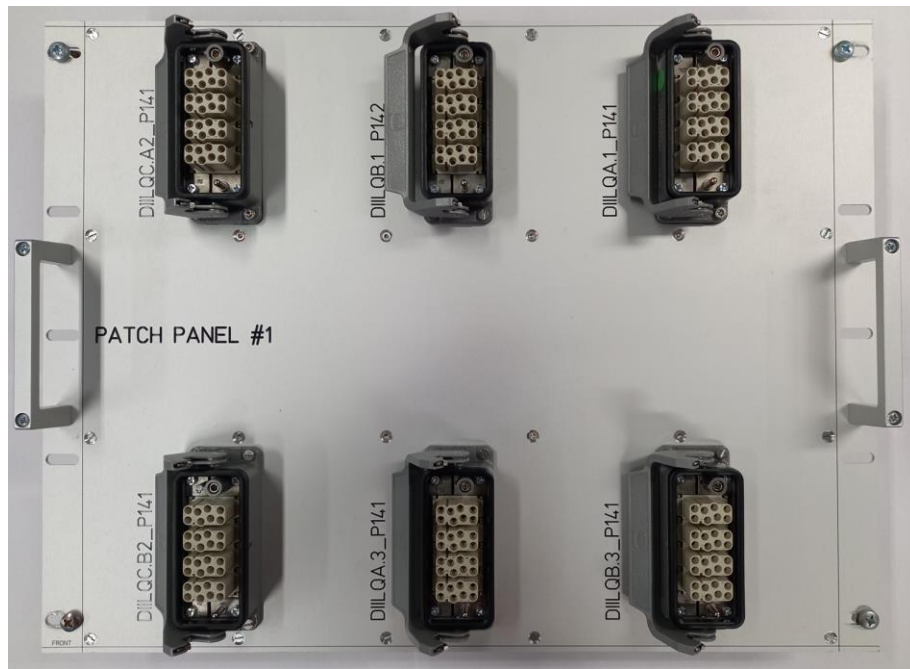
- UQDS → according to the configuration needed for each protection unit.
- ELQA → reproducing on a dedicated area the same pin-out/connector configuration as for the IFS boxes for each magnet.
- Another patch panel from a different rack.



View of the Patch Panel

All the Patch Panels are different between each other; every rack has its own patch panel.

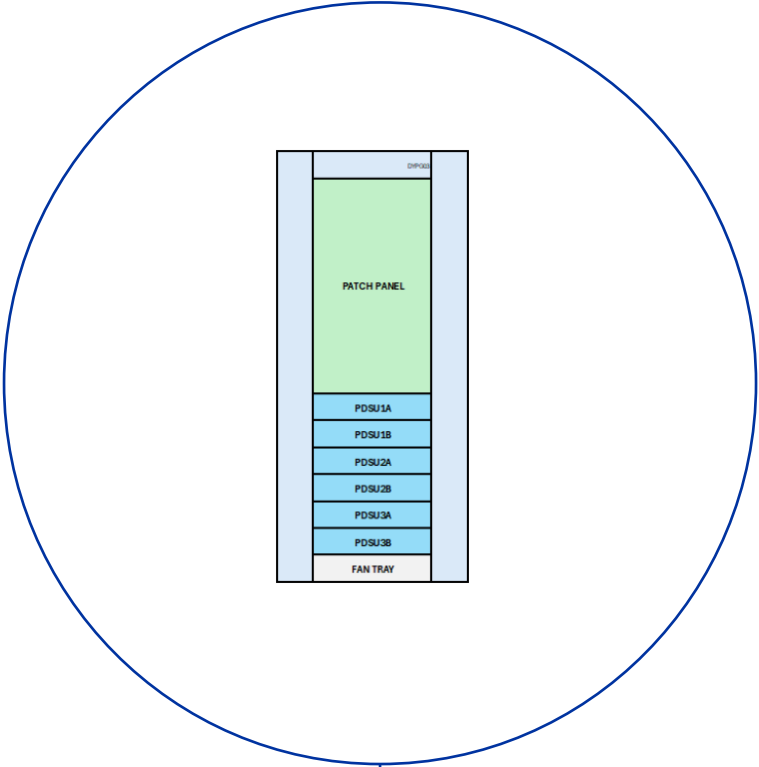
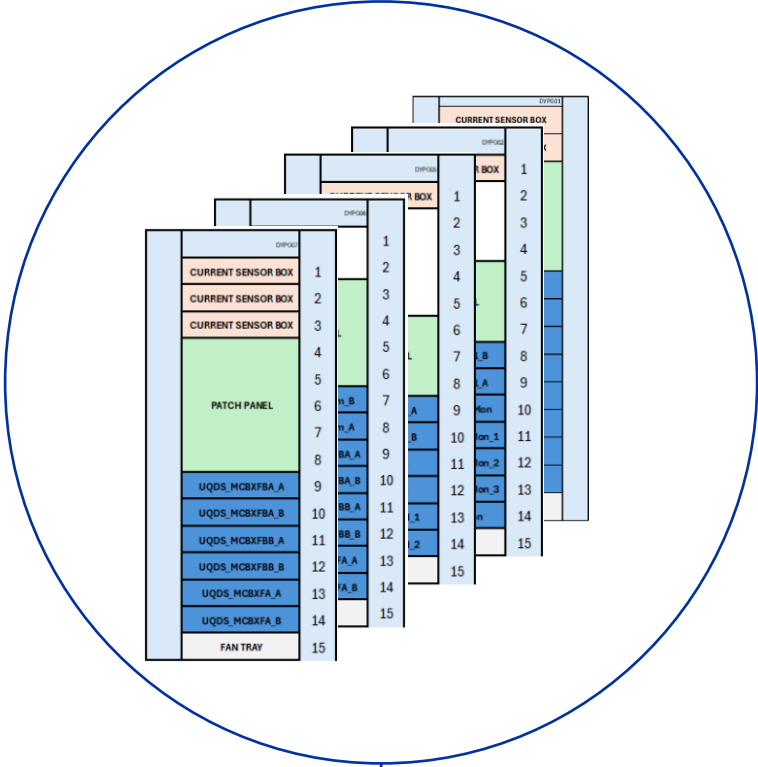
Front side: ELQA measurements



Back side: Input / Output current sensors / other racks



IT-STRING Patch Panel



Universal Quench Detection System

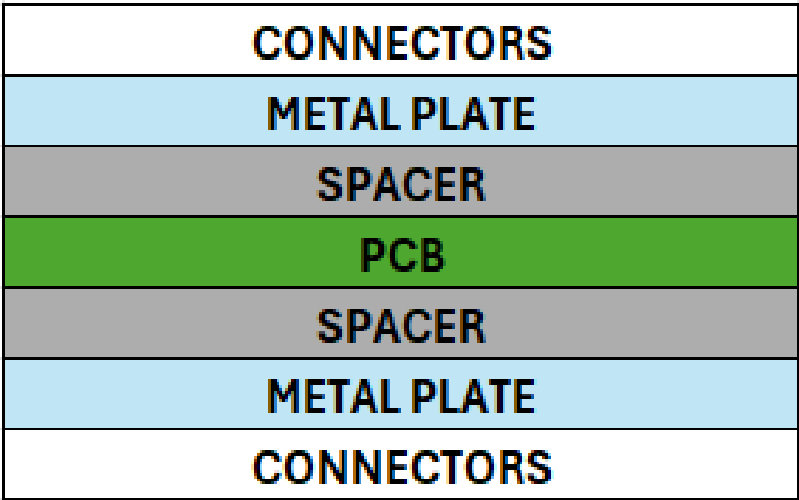
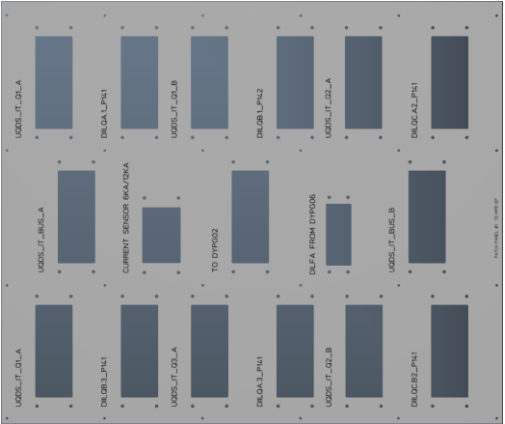
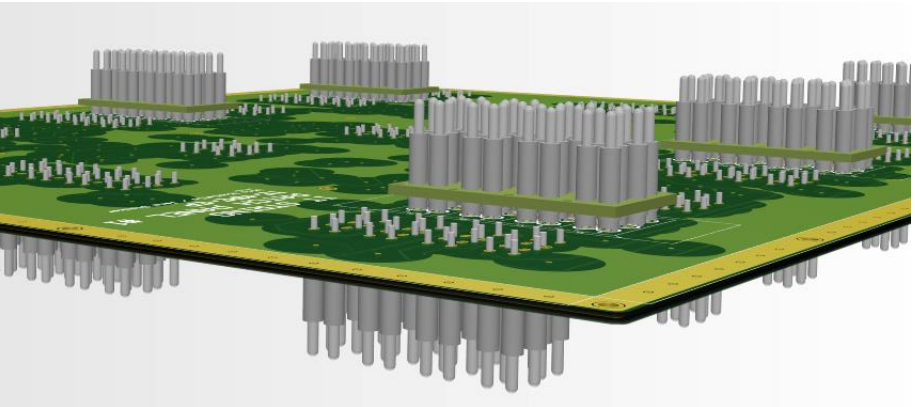
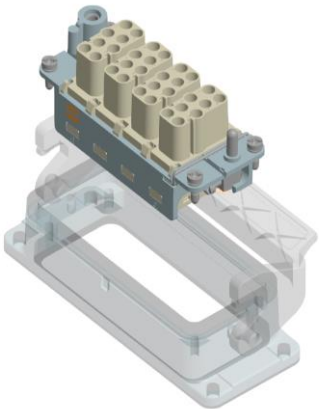


Protection Device Supervision Unit



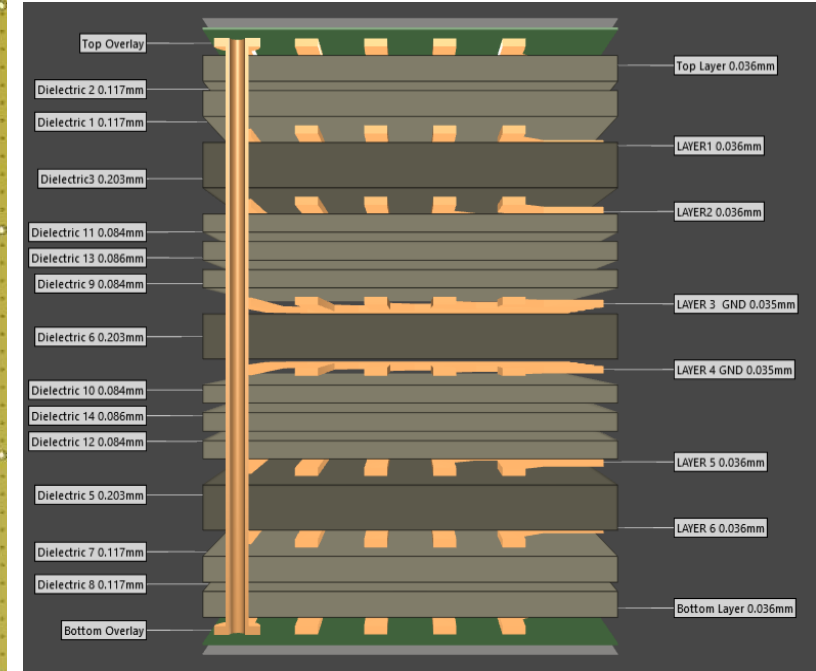
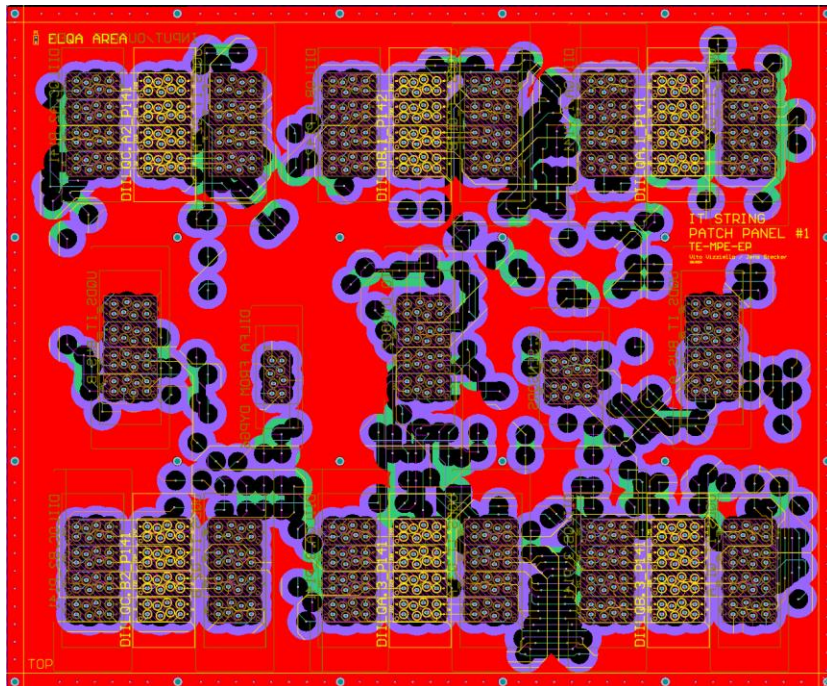
Development of the Patch Panel

- All PCB based (no wires).
- PCB is housed in a sandwich: Metal plate, spacer, PCB, spacer, Metal plate.
- Connector housings are mounted on the metal plate, both sides, and are connected directly to the PCB via the pin-matrix.



Development of the PCB

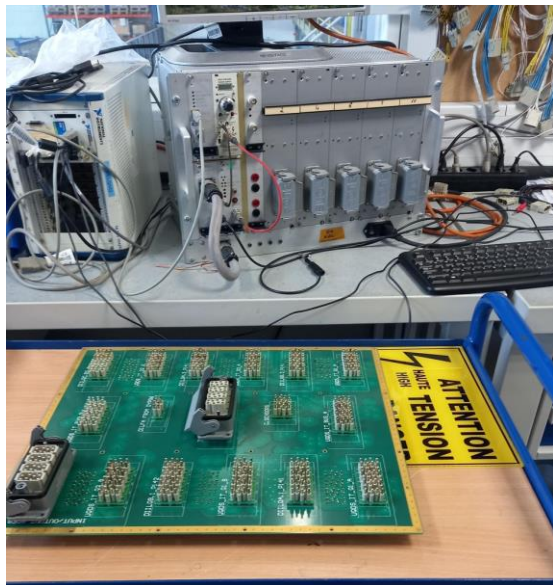
- PCB size: 3U, 6U, 9U
- Number of layers of the PCB: 8
- Number of dielectric layers: 13



HV test validation

HV test validation by TE-MPE-PE

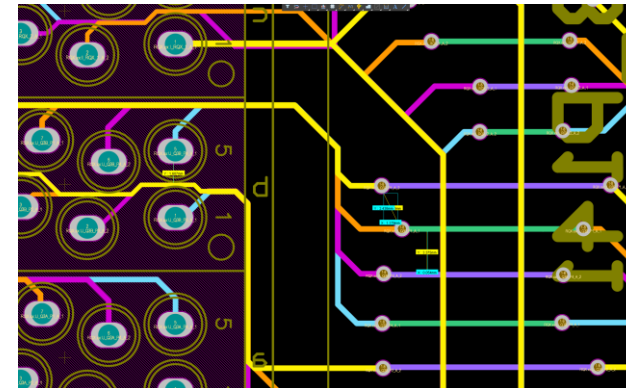
- The QDS Input Patch Panel must withstand a minimum of 2.5 kV for 60 s with no breakdown and a maximum leakage current of 10 μ A.
- Each connector at 1 kV must have a leakage current of less than 0.1 μ A after 60 s.



EDMS NO.	REV.	VALIDITY
282470	1.0	VALID
REFERENCE: LHC-D-ES-0015		

ENGINEERING SPECIFICATION		
MAGNET CIRCUIT FORUM		
ELECTRICAL DESIGN CRITERIA FOR THE HL-LHC CIRCUIT COMPONENTS OPERATING AT ROOM TEMPERATURE		
Abstract This document describes the strategy to be applied in order to define the voltage withstand levels of the equipment operating at Room Temperature (RT) that are electrically connected to the HL-LHC magnet circuits. The values presented in the document shall be the reference for the reception and qualification tests during installation and commissioning in the HL-LHC IT-Sring test and in the tunnel.		
TRACEABILITY		
Prepared by: M. J. Bednarek and S. Yammine	Date: 2023-03-21	
Verified by: D. Carrillo, G. D'Angelo, L. De Malleo, R. Deniz, J. Emonds-Ali, J. Fleiter, V. Guhler, L. Grand-Clement, E. Nowak, B. Paneo, M. Pojer, M. Silva Marreiros, L. Tavian, M. Theisen and A. Vozniak	Date: 2023-06-23	
Approved by: M. Martino, V. Montabonet, F. Rodriguez Mateos, O. Wollmann and M. Zierlath	Date: 2024-02-21	
Classification: MCF Isobars, HL LHC PD		
Rev. No.	Date	Description of Changes
0.2	2023-03-21	First version for engineering check
0.9	2023-08-07	Revision following engineering check round for approval
1.0	2024-02-21	Released version after approval round

Page 1 of 10 Template EDMS No. 131138



#	Name
	Top Overlay
	Top Solder
1	Top Layer
	Dielectric 2
2	LAYER1
	Dielectric3
3	LAYER2
	Dielectric 13
	Dielectric 9
4	LAYER 3 GND
	Dielectric 6
5	LAYER 4 GND
	Dielectric 10
	Dielectric 14
6	LAYER 5
	Dielectric 5
7	LAYER 6
	Dielectric 8
8	Bottom Layer
	Bottom Solder
	Bottom Overlay

Thank you



home.cern